MIRROR SEMICONDUCTOR AND MICROBONDS ANNOUNCE ALLIANCE ON MIRRORED PINOUT INTEGRATED CIRCUITS AND X-WIRE™ TECHNOLOGY

Irvine, California & Toronto, CANADA, (March 7, 2007) -- Mirror Semiconductor, a privately held fabless start up and Microbonds Inc. (a privately held Canadian corporation) are pleased to announce a co-development project to align existing products and technology for Mirror Semiconductor's "Mirrored Pinout" integrated circuits using Microbonds' X-Wire ™ insulated bonding wire technology.

Today's IC designs and board designs are pushing the limits of current technologies as the industry continues to decrease geometries and costs while increasing functionality and interconnect densities. Providing package designers and board designers with the flexibility to solve these issues effectively necessitates collaborative development between adjacent processes and technologies. The joint engineering effort to optimize the process window for Mirror Semiconductor with Microbonds' insulated wire bond technology will provide customers with added benefits such as reverse wire bonding, circuit board shrink with fewer inner layers, faster speed and enable solutions in all commonly available device packages.

"Insulated bonding wire will enable our"Mirrored Pinout' IC devices to meet our customers demands for smaller, faster and cheaper board level designs," said Martin Hart-, president of Mirror Semiconductor. "The ability of insulated wire to allow greater interconnect density using reverse bonding without the risk of shorting, provides our customers with a predictable product roadmap. X-Wire Technology allows Mirror Semiconductor to advance our roadmap while taking advantage of our existing IP", Hart added.

John Scott, CEO of Microbonds noted, "Mirror Semiconductor's innovative technology of Mirrored Pinout products demonstrates the capabilities of insulated bonding wire to enable wire bonding

with crossing wires to make the Mirrored Pinout packages without the risk of shorting. We are very pleased to have the opportunity to work with Mirror Semiconductor to advance their products and services".

About Mirror Semiconductor

Mirror Semiconductor is being launched as a joint venture between Liberty University and TopLine Corporation. Mission is to be a fabless producer of "Mirrored Pinout" integrated circuits and to license Mirrored Pinout technology to ODM, IDM, EMS, OEM and packaging foundries. Our web site address is www.mirrorsemi.com

About Microbonds

Microbonds, Inc. is the leading developer and licensor of insulated wire bonding technologies for use in the design and assembly of microelectronic devices. Our web site address is www.microbonds.com

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